

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSB015N04NX3 G	**Issued**	11. November 2019
MA#	MA000629696		
Package	MG-WDSON-2-8	**Weight***	86.37 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	6.356	7.36	7.36	73594	73594
leadframe	non noble metal	copper	7440-50-8	74.415	86.17	86.17	861570	861570
leadfinish	non noble metal	nickel	7440-02-0	0.211	0.24		2445	
	noble metal	silver	7440-22-4	0.840	0.97	1.21	9725	12170
plating	non noble metal	nickel	7440-02-0	0.211	0.24	0.24	2445	2445
solder	non noble metal	copper	7440-50-8	0.011	0.01		127	
	noble metal	silver	7440-22-4	0.066	0.08		763	
	non noble metal	tin	7440-31-5	2.119	2.45	2.54	24528	25418
glue	plastics	acrylic resin	-	0.254	0.29		2942	
	noble metal	silver	7440-22-4	1.561	1.81	2.10	18071	21013
passivation	plastics	epoxy resin	-	0.327	0.38	0.38	3790	3790
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com